

PATENT ASSIGNMENT

Electronic Version v07
 Stylesheet Version v02

SUBMISSION TYPE:		NEW ASSIGNMENT	APPLICATION NUMBER 10/605478		
NATURE OF CONVEYANCE:		ASSIGNMENT OF ASSIGNOR'S INTEREST			
CONVEYING PARTY DATA					
Name		Execution Date			
Hsiu-Chuan Chu		2003-09-26			
Chih-An Huang		2003-09-26			
Teng-Chun Tsai		2003-09-26			
Neng-Kuo Chen		2003-09-26			
RECEIVING PARTY DATA					
Name	Street Address	Internal Address	City	State/Country	Postal Code
United Microelectronics Corp.	No. 3, Li-Hsin Rd. II, Science-Based Industrial Park		Hsinchu	TAIWAN	
CORRESPONDENCE DATA					
FAX NUMBER: 886223697233					
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>					
When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO.					
CUSTOMER NUMBER: 031561					
NAME OF PERSON SIGNING:		Belinda Lee			
DATE SIGNED:		2003-10-02			
Total Attachments: 2 source=12157assignment2.tif source=12157assignment1.tif					

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ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Hsiu-Chuan Chu

Sole or First Joint Inventor: Hsiu-Chuan Chu

Sept. 26, 2003

Date:

Signature: Chih-An Huang

Second Joint Inventor (if any): Chih-An Huang

Sept. 26, 2003

Date:

Signature: Teng-Chun Tsai

Third Joint Inventor (if any): Teng-Chun Tsai

Sept. 26, 2003

Date:

Signature: Neng-Kuo Chen

Fourth Joint Inventor (if any): Neng-Kuo Chen

Sept. 26, 2003

Date:

ASSIGNMENT

WHEREAS,

- | | |
|-------------------|------------------|
| 1. Hsiu-Chuan Chu | 2. Chih-An Huang |
| 3. Teng-Chun Tsai | 4. Neng-Kuo Chen |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **SILICON OXIDE GAP-FILLING PROCESS**

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, United Microelectronics Corp.
of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.